ON Semiconductor



Initial Product/Process Change Notification Document # : IPCN20889B

Issue Date: 4 June 2015

Title of Change:	WLP fab site change from Gunma, Japan to Niigata, Japan				
Proposed first ship date:	15 February 2016				
Contact information:	Contact your local ON Semiconductor Sales Office or <u>Hiroshi.Kojima@onsemi.com</u>				
Samples:	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office or <u>Makoto.Nakaoka@onsemi.com</u>				
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>				
Change Part Identification:	Product lots will be identified through a date code marked on the parts				
Change category(s): Uafer Fab Change Assembly Change Test Change	Manufacturing Site Change/Addition Manufacturing Process Change Material Change	 Product specific change Datasheet/Product Doc change Shipping/Packaging/Marking Other: 			
Sites Affected: All site(s) not applicable ON Semiconductor site(s) : External Foundry/Subcon site		<u>Site 2</u>			
Description and Purpose:					

To continuously supply products and increase our supply capacity to support increased demand, the Wafer level package location will move from Gunma, Japan to Niigata, Japan. Most equipment and personnel will be transferred from the Gunma to the Niigata site. The Niigata site is ISO/TS16949 certified. Neither change in electrical characteristics, nor product reliably is expected.



Qualification Plan:

Estimated date for qualification completion: 13 November 2015

IC Reliability Plan

1.0

REFERENCE DOCUMENTS: 12MSB17722C - Product Reliability Qualification Process Specification

2.0

WLP/FLIP Reliability Plan

Fab site change from Gunma, Japan to Niigata, Japan

3.0

	WLCSP179		
Package	WLCSP36	Wafer Fab Site	Niigata
	WLFCP6		

4.0

RELIABILITY TESTING REQUIREMENTS

Test	Test Conditions	End Point Requirements	Sample Size	# of Lots	Total Units	Comments
HTOL	TJ ~ 150°C, for 1008 hrs	Test @ Room	77	3	231	
HTSL	150°C for 1008 hrs	Test @ Room	77	3	231	
ТНВ	85°C/85% RH for 1008 hrs	Test @ Room	77	3	231	
тс	-40°C to +125°C for 500 cycles	Test @ Room	77	3	231	

Samples should be available after completion of Qualification.

List of affected Standard Parts: LV52130A0XA-VH LV52130A4XA-VH

> LV52130N0XA-VH LV52130N4XA-VH LV52207NXA-VH LV52207XA-VH